

Ruey-Beei Wu

List of Publications by Year in descending order

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199
papers

3,371
citations

126907
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175258
52
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199
all docs

199
docs citations

199
times ranked

1816
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 1 | Optimization and Evaluation of Multidetector Deep Neural Network for High-Accuracy Wi-Fi Fingerprint Positioning. IEEE Internet of Things Journal, 2022, 9, 15204-15214. | 8.7 | 2 |
| 2 | Positioning for Search and Rescue in GPS-Denied Area by Distributed WiFi RSS-Based DoA Modules. IEEE Access, 2022, 10, 76105-76113. | 4.2 | 2 |
| 3 | Design for Acoustic Wave Multiplexers With Single Inductor Matching Network Using Frequency Response Fitting Method. IEEE Open Journal of Ultrasonics, Ferroelectrics, and Frequency Control, 2022, 2, 140-151. | 1.4 | 4 |
| 4 | Modeling and Mitigating Fiber Weave Effect Using Layer Equivalent Model and Monte Carlo Method. , 2022, , . | | 0 |
| 5 | Symmetric-Cell EBG Theory and Its Applications to Vias Daisy Chain for Residual Stub Detection. , 2022, , . | | 0 |
| 6 | Systematic Design for Mitigation of RF Desense by Interleaved Power Line in Two-Layer PCB. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 859-864. | 2.5 | 1 |
| 7 | Physical Tampering Detection Using Single COTS Wi-Fi Endpoint. Sensors, 2021, 21, 5665. | 3.8 | 7 |
| 8 | Synthesis of Chebyshev/Elliptic Filters Using Minimum Acoustic Wave Resonators. IEEE Access, 2019, 7, 103456-103462. | 4.2 | 14 |
| 9 | Nonperiodic Flipped EBG for Dual-Band SSN Mitigation in Two-Layer PCB. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1690-1697. | 2.5 | 5 |
| 10 | A Phenomenological Approach Based on Two Unified Loss Parameters for Transient Analysis of Transmission Lines. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2219-2226. | 2.5 | 1 |
| 11 | A Novel Desensitization Using Resonance Suppressors in Metallic Shielding. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1680-1689. | 2.5 | 2 |
| 12 | SI Analysis of Electro-Optic Interconnects for Next Generation SerDes in WLP-SiP. , 2019, , . | | 0 |
| 13 | Reduction of Common-Mode Noise in Bent Differential Interconnects for PAM4 Signaling. , 2019, , . | | 0 |
| 14 | An Interactive Web-based Learning Module for Metallic Rectangular Waveguides. , 2019, , . | | 0 |
| 15 | Interleaved Power Transmission Line for Mitigation of Digital to RF De-sense. , 2019, , . | | 2 |
| 16 | A Novel Dual-Sided Fly-By Topology for 1â€“8 DDR With Optimized Signal Integrity by EBG Design. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1823-1829. | 2.5 | 7 |
| 17 | Miniaturized Tunable Filters with T-Coil Design. , 2018, , . | | 0 |
| 18 | Non-Periodic Flipped-SIR EBG for Dual-Band SSN Mitigation in 2-Layer PCB. , 2018, , . | | 1 |

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 19 | Suppression of noise from digital-to-analog coupling in shielding cavity. , 2018, , . | | 1 |
| 20 | Novel RDL Design of Wafer-Level Packaging for Signal/Power Integrity in LPDDR4 Application. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1431-1439. | 2.5 | 10 |
| 21 | Three-way cascade power divider and combiner for satellite communications. , 2017, , . | | 8 |
| 22 | The competitions of electromagnetic for undergraduate students in Taiwan: Taiwan creative electromagnetic implementation competition T-CEIC. , 2017, , . | | 0 |
| 23 | A Novel Two-Cap Filter for Routing Noise Suppression Using Extended EBG Analysis. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1852-1858. | 2.5 | 3 |
| 24 | A 77-GHz 2T6R Transceiver With Injection-Lock Frequency Sextupler Using 65-nm CMOS for Automotive Radar System Application. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 3031-3048. | 4.6 | 55 |
| 25 | Varactor-Tuned Compact Dual-Mode Tunable Filter With Constant Passband Characteristics. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1399-1407. | 2.5 | 40 |
| 26 | Design of compact microwave filter using vertically interdigitated resonators. , 2015, , . | | 0 |
| 27 | Design of 2-in-1 bandpass filter using common dual mode resonators. , 2015, , . | | 0 |
| 28 | A miniaturized bandpass filter using double folded dual-mode cavity resonators in LTCC. , 2015, , . | | 0 |
| 29 | Design of stackup and shorting vias and for reducing edge radiation in multilayer PCB. , 2015, , . | | 1 |
| 30 | Ring Noise Suppression for Differential Signaling in Unshielded Flexible Flat Cable. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 1152-1159. | 2.5 | 3 |
| 31 | Artificial neural network modeling for Extrinsic capacitance of FinFET. , 2014, , . | | 0 |
| 32 | Efficient multi-node optimal placement for decoupling capacitors on PCB. , 2014, , . | | 6 |
| 33 | Modeling and Fast Eye Diagram Estimation of Ringing Effects on Branch Line Structures. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 641-647. | 2.5 | 1 |
| 34 | Fast Prediction and Optimal Design for Eye-Height Performance of Mismatched Transmission Lines. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 896-904. | 2.5 | 6 |
| 35 | Triband Filter Design Using Laminated Waveguide Cavity in LTCC. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 957-966. | 2.5 | 26 |
| 36 | Design of Single-Branch Laminated Waveguide Diplexers Using Modal Orthogonality. IEEE Transactions on Microwave Theory and Techniques, 2013, 61, 4079-4089. | 4.6 | 28 |

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 37 | Development of millimeter-wave passive components and system-in-packages by LTCC technology. , 2013, , . | | 0 |
| 38 | Characterization of TSVs by cascaded daisy chains. , 2013, , . | | 0 |
| 39 | Design of a 180-degree hybrid with Chebyshev filtering response using coupled resonators. , 2013, , . | | 14 |
| 40 | Design of Miniaturized Filtering Power Dividers for System-in-a-Package. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1663-1672. | 2.5 | 101 |
| 41 | Millimeter-wave non-contact flip-chip transitions with Chebyshev filtering response using coupled microstrip resonators. , 2013, , . | | 0 |
| 42 | Modified pseudo eye metric for mismatched transmission lines. , 2013, , . | | 0 |
| 43 | Development of wideband electrically identical fan-out structure for 60 GHz frontend phased array system in package module. , 2012, , . | | 1 |
| 44 | An integrated filtering antenna array with 180 degree hybrid for SiP front end module. , 2012, , . | | 4 |
| 45 | Enhanced eye-height estimation of mismatched lossy transmission lines. , 2012, , . | | 2 |
| 46 | A compact filtering rat-race coupler using dual-mode stub-loaded resonators. , 2012, , . | | 19 |
| 47 | 60-GHz Four-Element Phased-Array Transmit/Receive System-in-Package Using Phase Compensation Techniques in 65-nm Flip-Chip CMOS Process. IEEE Transactions on Microwave Theory and Techniques, 2012, 60, 743-756. | 4.6 | 177 |
| 48 | Design considerations for radio frequency 3DICs. , 2012, , . | | 0 |
| 49 | A linear 4-element model of VRM —Characteristics, practical uses and limitations. , 2012, , . | | 7 |
| 50 | Antenna Design of 60-GHz Micro-Radar System-In-Package for Noncontact Vital Sign Detection. IEEE Antennas and Wireless Propagation Letters, 2012, 11, 1702-1705. | 4.0 | 42 |
| 51 | LTCC embedded laminated waveguide filters and couplers for microwave SiP applications. , 2011, , . | | 0 |
| 52 | Design of Microstrip-to-Microstrip Via Transition in Multilayered LTCC for Frequencies up to 67 GHz. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 595-601. | 2.5 | 50 |
| 53 | Passive Equalizer Design for Through Silicon Vias With Perfect Compensation. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1815-1822. | 2.5 | 19 |
| 54 | Design of Multimode Net-Type Resonators and Their Applications to Filters and Multiplexers. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 848-856. | 4.6 | 65 |

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 55 | Design of Compact Quadruplexer Based on the Tri-Mode Net-Type Resonators. IEEE Microwave and Wireless Components Letters, 2011, 21, 534-536. | 3.2 | 62 |
| 56 | Modeling and Optimal Design of Shorting Vias to Suppress Radiated Emission in High-Speed Alternating PCB Planes. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 566-573. | 2.5 | 16 |
| 57 | Direct Eye Diagram Optimization for Arbitrary Transmission Lines Using FIR Filter. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1250-1258. | 2.5 | 18 |
| 58 | Passive FIR filter design using reflections from stubs for high speed links. , 2011, , . | | 0 |
| 59 | A Laminated Waveguide Magic-T With Bandpass Filter Response in Multilayer LTCC. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 584-592. | 4.6 | 51 |
| 60 | Design of quadruple-passband microwave filters using frequency transformation. , 2011, , . | | 0 |
| 61 | Optimal decoupling capacitors design for suppressing edge radiation of power/ground planes. , 2011, , . | | 3 |
| 62 | SI-aware layout and equalizer design to enhance performance of high-speed links in blade servers. , 2011, , . | | 5 |
| 63 | A New Isolation Structure of Pogo Pins for Crosstalk Reduction in a Test Socket. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 586-594. | 2.5 | 15 |
| 64 | Signal/Power Integrity Modeling of High-Speed Memory Modules Using Chip-Package-Board Coanalysis. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 381-391. | 2.2 | 28 |
| 65 | Optimization of FIR filter to improve eye diagram for general transmission line systems. , 2010, , . | | 2 |
| 66 | Enhanced Microstrip Guard Trace for Ringing Noise Suppression Using a Dielectric Superstrate. IEEE Transactions on Advanced Packaging, 2010, 33, 961-968. | 1.6 | 26 |
| 67 | Compromise Impedance Match Design for Pogo Pins With Different Single-Ended and Differential Signal-Ground Patterns. IEEE Transactions on Advanced Packaging, 2010, 33, 953-960. | 1.6 | 12 |
| 68 | A Wideband Common-Mode Suppression Filter for Bend Discontinuities in Differential Signaling Using Tightly Coupled Microstrips. IEEE Transactions on Advanced Packaging, 2010, 33, 969-978. | 1.6 | 67 |
| 69 | Tri-band filter design using substrate integrated waveguide resonators in LTCC. , 2010, , . | | 9 |
| 70 | RC passive equalizer for through silicon via. , 2010, , . | | 3 |
| 71 | A new isolation structure for crosstalk reduction of pogo pins in a test socket. , 2009, , . | | 4 |
| 72 | Dual-Band Vertically Stacked Laminated Waveguide Filter Design in LTCC Technology. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 1554-1562. | 4.6 | 76 |

| # | ARTICLE | IF | CITATIONS |
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| 73 | Miniaturized Bandpass Filters With Double-Folded Substrate Integrated Waveguide Resonators in LTCC. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 1774-1782. | 4.6 | 99 |
| 74 | Design of Tri-Band Filters With Improved Band Allocation. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 1790-1797. | 4.6 | 67 |
| 75 | A system-on-package integration of X-band FMCW sensor RF frontend module. , 2009, , . | | 1 |
| 76 | Design of shorting vias in alternative PCB planes for suppressing ground-bounce induced electromagnetic emission. , 2009, , . | | 1 |
| 77 | Design of lumped rat-race coupler in multilayer LTCC. , 2009, , . | | 17 |
| 78 | A wide-band microstrip-to-microstrip multi-layered via transition using LTCC technology. , 2009, , . | | 0 |
| 79 | A laminated waveguide magic-T in multilayer LTCC. , 2009, , . | | 6 |
| 80 | Compromised impedance match design for signal integrity of pogo pins structures with different signal-ground patterns. , 2009, , . | | 8 |
| 81 | Miniaturized rat-race coupler with bandpass response and good stopband rejection. , 2009, , . | | 34 |
| 82 | Fast Methodology for Determining Eye Diagram Characteristics of Lossy Transmission Lines. IEEE Transactions on Advanced Packaging, 2009, 32, 175-183. | 1.6 | 39 |
| 83 | Reduction in Reflections and Ground Bounce for Signal Line Over Slotted Power Plane Using Differential Coupled Microstrip Lines. IEEE Transactions on Advanced Packaging, 2009, 32, 581-588. | 1.6 | 21 |
| 84 | A Dual Wideband Filter Design Using Frequency Mapping and Stepped-Impedance Resonators. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 2921-2929. | 4.6 | 60 |
| 85 | Highly Directed Radiation Pattern From a THz Photonic Transmitter With a Two-Dimensional Rampart Slot Array Antenna. IEEE Photonics Technology Letters, 2008, 20, 1042-1044. | 2.5 | 1 |
| 86 | Fewest vias design for microstrip guard trace by using overlying dielectric. , 2008, , . | | 16 |
| 87 | Placement of shorting vias for power integrity in multi-layered structures. , 2008, , . | | 0 |
| 88 | Reflection Enhanced Compensation of Lossy Traces for Best Eye-Diagram Improvement Using High-Impedance Mismatch. IEEE Transactions on Advanced Packaging, 2008, 31, 619-626. | 1.6 | 23 |
| 89 | The effects on SI and EMI for differential coupled microstrip lines over LPC-EBG power/ground planes. , 2008, , . | | 4 |
| 90 | Delaunay's Voronoi Modeling of Power-Ground Planes With Source Port Correction. IEEE Transactions on Advanced Packaging, 2008, 31, 303-310. | 1.6 | 43 |

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| 91 | Signal integrity analysis of DDR3 high-speed memory module. , 2008, , . | | 8 |
| 92 | Designs of signal-ground bump-patterns for minimizing the simultaneous switching noise in a ball grid array. , 2008, , . | | 1 |
| 93 | Multilayer 180°; hybrid in LTCC. , 2008, , . | | 2 |
| 94 | Design of Reflectionless Vias Using Neural Network-Based Approach. IEEE Transactions on Advanced Packaging, 2008, 31, 211-218. | 1.6 | 15 |
| 95 | Highly-directed terahertz photonic transmitter by using the design of planar antenna arrays. , 2008, , . | | 0 |
| 96 | Design of Compact Branch-Line Coupler with Coupled Resonators. , 2007, , . | | 15 |
| 97 | A Vertically Stacked Quasi-Elliptic Waveguide Filter with Crossly Coupling Vias. , 2007, , . | | 7 |
| 98 | The microwave activity and progress in National Taiwan University. , 2007, , . | | 0 |
| 99 | Fast Algorithm for Determining Eye-Diagram Characteristics of Lossy Transmission Lines. , 2007, , . | | 2 |
| 100 | Design of A Vertically Stacked Substrate Integrated Folded-Waveguide Resonator Filter in LTCC. , 2007, , . | | 7 |
| 101 | An Integrated Signal and Power Integrity Analysis for Signal Traces Through the Parallel Planes Using Hybrid Finite-Element and Finite-Difference Time-Domain Techniques. IEEE Transactions on Advanced Packaging, 2007, 30, 558-565. | 1.6 | 15 |
| 102 | Design of 30GHz Transition between Microstrip Line and Substrate Integrated Waveguide. , 2007, , . | | 9 |
| 103 | Reflectionless Design for Differential-Via Transitions Using Neural Network-Based Approach. , 2007, , . | | 5 |
| 104 | Microwave Activities in Taiwan. IEEE MTT-S International Microwave Symposium Digest IEEE MTT-S International Microwave Symposium, 2007, , . | 0.0 | 0 |
| 105 | Improvements of Time-Domain Transmission Waveform in Serpentine Delay Line with Guard Traces. , 2007, , . | | 6 |
| 106 | A Dual Pass Band Filter with Embedded CPW Resonator. , 2007, , . | | 0 |
| 107 | Design of Vertically Stacked Waveguide Filters in LTCC. IEEE Transactions on Microwave Theory and Techniques, 2007, 55, 1771-1779. | 4.6 | 65 |
| 108 | Novel compact net-type resonators and their applications to microstrip bandpass filters. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 755-762. | 4.6 | 47 |

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| 109 | Design of Wideband Impedance Matching for Through-Hole Via Transition Using Ellipse-Shaped Anti-Pad. , 2006, , . | | 20 |
| 110 | An Efficient and Flexible Modeling for Power/Ground Planes. , 2006, , . | | 1 |
| 111 | A Systematic Design to Suppress Wideband Ground Bounce Noise in High-Speed Circuits by Electromagnetic-Bandgap-Enhanced Split Powers. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 4209-4217. | 4.6 | 44 |
| 112 | Comparisons between serpentine and flat spiral delay lines on transient reflection/transmission waveforms and eye diagrams. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 1379-1387. | 4.6 | 42 |
| 113 | Terahertz Microchip for Illicit Drug Detection. IEEE Photonics Technology Letters, 2006, 18, 2254-2256. | 2.5 | 44 |
| 114 | Frequency tunability of terahertz photonic transmitters. Applied Physics Letters, 2006, 88, 093501. | 3.3 | 8 |
| 115 | Design of a vertically stacked waveguide filter with novel cross coupling structures in LTCC. , 2006, , . | | 5 |
| 116 | Microstrip diplexers design with common resonator sections for compact size, but high isolation. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 1945-1952. | 4.6 | 230 |
| 117 | Steady-state response by finite-difference time-domain method and lanczos algorithm. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 3038-3044. | 4.6 | 2 |
| 118 | Miniaturized Microstrip Quasi-Elliptical Bandpass Filters Using Slotted Resonators. , 2006, , . | | 6 |
| 119 | Hybrid TIE/FDTD Method for Open Boundary Coupling Between Isolation Islands. IEEE Transactions on Advanced Packaging, 2006, 29, 623-630. | 1.6 | 1 |
| 120 | A miniaturized microstrip common resonator triplexer without extra matching network. , 2006, , . | | 17 |
| 121 | Terahertz biochip for illicit drug detection. , 2006, , . | | 0 |
| 122 | Noise Reduction Using Compensation Capacitance for Bend Discontinuities of Differential Transmission Lines. IEEE Transactions on Advanced Packaging, 2006, 29, 560-569. | 1.6 | 80 |
| 123 | A miniaturized multilayer quasi-elliptic bandpass filter with aperture-coupled microstrip resonators. IEEE Transactions on Microwave Theory and Techniques, 2005, 53, 2688-2692. | 4.6 | 26 |
| 124 | Design of microstrip bandpass filters with multiorder spurious-mode suppression. IEEE Transactions on Microwave Theory and Techniques, 2005, 53, 3788-3793. | 4.6 | 182 |
| 125 | Ka-band 32-GHz planar integrated switched-beam smart antenna. , 2005, , . | | 2 |
| 126 | Bandwidth enhancement on waveguide transition to conductor backed CPW with high dielectric constant substrate. IEEE Microwave and Wireless Components Letters, 2005, 15, 128-130. | 3.2 | 17 |

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| 127 | Broadband-response and frequency-tunable terahertz photonic transmitters with high efficiency. , 2005, , . | | 1 |
| 128 | A miniaturized net-type microstrip bandpass filter using $\lambda/8$ resonators. IEEE Microwave and Wireless Components Letters, 2005, 15, 481-483. | 3.2 | 17 |
| 129 | A dual band elliptical DRA. , 2004, , . | | 2 |
| 130 | Synthesis of nonuniformly spaced linear array for GSM/DCS/WCDMA base station application using genetic algorithm. , 2004, , . | | 5 |
| 131 | A Circular Polarizer Designed With a Dielectric Septum Loading. IEEE Transactions on Microwave Theory and Techniques, 2004, 52, 1719-1723. | 4.6 | 63 |
| 132 | A 650 GHz photonic transmitter design using CPW-fed slot antenna. , 2004, , . | | 0 |
| 133 | Device Saturation Behavior of Submillimeter-Wave Membrane Photonic Transmitters. IEEE Photonics Technology Letters, 2004, 16, 873-875. | 2.5 | 15 |
| 134 | Millimeter-Wave MMIC Passive HEMT Switches Using Traveling-Wave Concept. IEEE Transactions on Microwave Theory and Techniques, 2004, 52, 1798-1808. | 4.6 | 82 |
| 135 | Reduction in reflections and ground bounce for signal line through a split power plane by using differential coupled microstrip lines. , 2003, , . | | 9 |
| 136 | An improved formalism for FDTD analysis of thin-slot problems by conformal mapping technique. IEEE Transactions on Antennas and Propagation, 2003, 51, 2530-2533. | 5.1 | 24 |
| 137 | Modeling and design for electrical performance of wideband flip-chip transition. IEEE Transactions on Advanced Packaging, 2003, 26, 385-391. | 1.6 | 42 |
| 138 | A Broadband Microstrip-to-Waveguide Transition with Tapered CPS Probe. , 2002, , . | | 13 |
| 139 | Highly Selective Microstrip Bandpass Filters in Ka-Band. , 2002, , . | | 17 |
| 140 | Composite effects of reflections and ground bounce for signal line through a split power plane. IEEE Transactions on Advanced Packaging, 2002, 25, 297-301. | 1.6 | 18 |
| 141 | CPW to waveguide transition with tapered slotline probe. IEEE Microwave and Wireless Components Letters, 2001, 11, 314-316. | 3.2 | 44 |
| 142 | Partially prism-gridded FDTD analysis for layered structures of transversely curved boundary. IEEE Transactions on Microwave Theory and Techniques, 2000, 48, 339-346. | 4.6 | 5 |
| 143 | Computations for radiation and surface-wave losses in coplanar waveguide bandpass filters. IEEE Transactions on Microwave Theory and Techniques, 1999, 47, 385-389. | 4.6 | 8 |
| 144 | The use of symmetry to simplify the mixed-potential integral-equation method with application to N-way radial power dividers/combiners with isolation resistors. IEEE Transactions on Microwave Theory and Techniques, 1999, 47, 1609-1616. | 4.6 | 7 |

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| 145 | A wide-band multiport planar power-divider design using matched sectorial components in radial arrangement. IEEE Transactions on Microwave Theory and Techniques, 1998, 46, 1072-1078. | 4.6 | 27 |
| 146 | Hybrid finite-difference time-domain modeling of curved surfaces using tetrahedral edge elements. IEEE Transactions on Antennas and Propagation, 1997, 45, 1302-1309. | 5.1 | 66 |
| 147 | Analysis of coplanar-waveguide discontinuities with finite-metallization thickness and nonrectangular edge profile. IEEE Transactions on Microwave Theory and Techniques, 1997, 45, 2131-2138. | 4.6 | 9 |
| 148 | Capacitance computation for CPW discontinuities with finite metallization thickness by hybrid finite-element method. IEEE Transactions on Microwave Theory and Techniques, 1997, 45, 498-504. | 4.6 | 13 |
| 149 | Modeling of microwave active devices using the FDTD analysis based on the voltage-source approach. , 1996, 6, 199-201. | | 70 |
| 150 | A wideband waveguide transition design with modified dielectric transformer using edge-based tetrahedral finite-element analysis. IEEE Transactions on Microwave Theory and Techniques, 1996, 44, 1024-1031. | 4.6 | 6 |
| 151 | Analysis of edge slots in rectangular waveguide with finite waveguide wall thickness. IEEE Transactions on Antennas and Propagation, 1996, 44, 1120-1126. | 5.1 | 16 |
| 152 | Flat spiral delay line design with minimum crosstalk penalty. IEEE Transactions on Advanced Packaging, 1996, 19, 397-402. | 0.6 | 37 |
| 153 | A hybrid spatial domain analysis of the Wilkinson power divider. , 1996, , . | | 2 |
| 154 | Full-wave characterization of a through hole via in multi-layered packaging. IEEE Transactions on Microwave Theory and Techniques, 1995, 43, 1073-1081. | 4.6 | 49 |
| 155 | Laddering wave in serpentine delay line. IEEE Transactions on Advanced Packaging, 1995, 18, 644-650. | 0.6 | 56 |
| 156 | A scalar variational conformal mapping technique for weakly guiding dielectric waveguides. IEEE Journal of Quantum Electronics, 1986, 22, 603-609. | 1.9 | 6 |
| 157 | Variational reaction formulation of scattering problem for anisotropic dielectric cylinders. IEEE Transactions on Antennas and Propagation, 1986, 34, 640-645. | 0.8 | 37 |
| 158 | Propagation of Waves through Magnetoplasrna Slab Within a Parallel-Plate Guide. IEEE Transactions on Microwave Theory and Techniques, 1986, 34, 32-37. | 4.6 | 3 |
| 159 | Birefringence Analysis of Anisotropic Optical Fibers Using Variational Reaction Theory. IEEE Transactions on Microwave Theory and Techniques, 1986, 34, 741-745. | 4.6 | 2 |
| 160 | On the Variational Reaction Theory for Dielectric Waveguides. IEEE Transactions on Microwave Theory and Techniques, 1985, 33, 477-483. | 4.6 | 17 |
| 161 | Scattering analysis of optical fibers in spectral domain. , 0, , . | | 0 |
| 162 | Full-Wave Iterative Variational Formulation for Multiple Coupled Microstrip Lines. , 0, , . | | 0 |

| # | ARTICLE | IF | CITATIONS |
|-----|--|----|-----------|
| 163 | Equivalent circuit of a through via in multi-layer environment. , 0, , . | | 3 |
| 164 | Full wave characterization of a through hole via discontinuity in multi-layered packaging. , 0, , . | | 3 |
| 165 | Laddering wave in serpentine delay line. , 0, , . | | 0 |
| 166 | Quick inspection of power-plane short fault on multichip module. , 0, , . | | 0 |
| 167 | A new flat spiral routing to minimize crosstalk penalty in delay line. , 0, , . | | 1 |
| 168 | Inspection of short fault in power-plane with irregular and perforated shapes [MCMs]. , 0, , . | | 0 |
| 169 | Electrical and mechanical studies of MCM-D interconnect structure. , 0, , . | | 1 |
| 170 | Hybridizing FD-TD analysis with unconditionally stable FEM for objects of curved boundary. , 0, , . | | 10 |
| 171 | Comparative performance of three different CPW bandpass filters. , 0, , . | | 6 |
| 172 | Equivalent inductances of coplanar-stripline step discontinuities. , 0, , . | | 0 |
| 173 | A wide band multiport planar power divider design by radially combining matched sectorial components. , 0, , . | | 2 |
| 174 | Hybrid FEM analysis of thick CPW discontinuities with nonrectangular cross section. , 0, , . | | 0 |
| 175 | A simplified MPIE analysis for planar circuits with N-fold rotational symmetry and lumped elements. , 0, , . | | 0 |
| 176 | Partially prism-gridded FDTD analysis for layered structures of transversely curved boundary. , 0, , . | | 1 |
| 177 | Treating late-time instability of partially tetrahedral-gridded finite difference time domain method. , 0, , . | | 0 |
| 178 | A resonant flip-chip design with controllable transition band. , 0, , . | | 2 |
| 179 | Composite effects of reflections and ground bounce for signal vias in multi-layer environment. , 0, , . | | 3 |
| 180 | Locally matching design for flip-chip transition. , 0, , . | | 1 |

| # | ARTICLE | IF | CITATIONS |
|-----|--|----|-----------|
| 181 | Hermetic housing design for TR module in LMDS system. , 0, , . | | 0 |
| 182 | Analysis of microstrip antennas with finite-sized substrate. , 0, , . | | 1 |
| 183 | Composite effects of reflections and ground bounce for signal line through a split power plane. , 0, , . | | 0 |
| 184 | A locally matching technique for broadband flip-chip transition design. , 0, , . | | 2 |
| 185 | Analysis of microstrip antennas with inhomogeneous and finite-sized substrate. , 0, , . | | 0 |
| 186 | Two-dimensional finite-difference time-domain method combined with open boundary for signal integrity issues between isolation islands. , 0, , . | | 3 |
| 187 | Steady-state response by time-reversal FD-TD method with Lanczos algorithm. , 0, , . | | 1 |
| 188 | Conversion efficiency and device behavior of edge-coupled membrane photonic transmitters. , 0, , . | | 0 |
| 189 | Modeling antenna array elements and bandwidth enhanced by genetic algorithm. , 0, , . | | 0 |
| 190 | Circuit modeling and noise reduction for bent differential transmission lines. , 0, , . | | 1 |
| 191 | Comparison between flat spiral and serpentine differential delay lines on TDR and TDT. , 0, , . | | 1 |
| 192 | A Wide-stopband Low-pass Filter Design Based on Multi-period Taper-etched EBG Structure. , 0, , . | | 2 |
| 193 | Compact Microstrip Cross-Coupled Bandpass Filters Using Miniaturized Stepped Impedance Resonators. , 0, , . | | 10 |
| 194 | Model Extractions of Coupled Bonding-wire Structures in Electronic Packaging. , 0, , . | | 5 |
| 195 | Combined FDTD/FETD algorithm for ground bounce characterization of differential traces through the planes. , 0, , . | | 0 |
| 196 | EBG-enhanced split power planes for wideband noise suppression. , 0, , . | | 2 |
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